Product / Package Information

Package	LGA_CAV
Body Size (mm)	3.76 X 4.72 X 1.0
Ball Count	6
Terminal Finish	Gold

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Lid/Shield

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Stainless steel	Iron	7439-89-6	8.55 E-03	65.77	657692	25.47	254695
Stainless steel	Chromium	7440-47-3	2.37 E-03	18.20	182000	7.05	70481
Stainless steel	Nickel	7440-02-0	1.05 E-03	8.04	80400	3.11	31135
Stainless steel	Manganese	7439-96-5	1.41 E-04	1.09	10862	0.42	4206
Stainless steel	Silicon	7440-21-3	6.73 E-05	0.52	5177	0.20	2005
Stainless steel	Carbon	7440-44-0	5.00 E-06	0.04	385	0.01	149
Stainless steel	Nitrogen	7727-37-9	4.40 E-06	0.03	338	0.01	131
Stainless steel	Phosphorus	7723-14-0	3.20 E-06	0.02	246	0.01	95
Stainless steel	Molybdenum	7439-98-7	2.60 E-06	0.02	200	0.01	77
Stainless steel	Sulfur	7704-34-9	4.00 E-07	0.003	31	0.001	12
Nickel & its alloys	Nickel	7440-02-0	3.62 E-04	2.785	27854	1.079	10787
Tin & its alloys	Tin	7440-31-5	4.53 E-04	3.482	34815	1.348	13482
Subtotal			1.30 E-02	100.0	1000000	38.726	387256

Laminate

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Composite	Fibrous glass-wool						
Composite	Bis(3-ethyl-5-methyl-4-maleimidophenyl)methane						
Composite	Triazine						
Composite	Phenolic Polymer Resin						
Composite	Aluminium hydroxide						
Composite	Laminate Subtotal	Proprietary	7.45 E-03	43.52	435219	22.20	222047
Other organic materials	Cured resin						
Other inorganic materials	Barium sulfate						
Other inorganic materials	Talc						
Other organic materials	Copper phthalocyanine blue						
Other inorganic materials	Silicon dioxide						
Other inorganic materials	Aluminium compounds						
Other organic materials	Solder Mask Subtotal	Proprietary	5.31 E-03	31.00	310037	15.82	158179
Copper & its alloys	Copper	7440-50-8	3.17 E-03	18.49	184854	9.43	94312
Nickel & its alloys	Nickel	7440-02-0	1.02 E-03	5.97	59672	3.04	30444
Precious Metals	Gold	7440-57-5	1.75 E-04	1.02	10218	0.52	5213
Subtotal			1.71 E-02	100.00	1000000	51.02	510195

Solder Land

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	5.90 E-04	74.68	746835	1.76	17575
Nickel & its alloys	Nickel	7440-02-0	1.70 E-04	21.52	215190	0.51	5064
Precious Metals	Gold	7440-57-5	3.00 E-05	3.80	37975	0.09	894
Subtotal			7.90 E-04	100.00	1000000	2.35	23533

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	9.90 E-05	99	990000	0.29	2949
Precious metals	Palladium	7440-05-3	1.00 E-06	1	10000	0.003	30
Subtotal			1.00 E-04	100	1000000	0.298	2979

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.30 E-03	100	1000000	3.87	38726

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	6.22 E-04	77.71	777100	1.85	18519
Thermoset	Epichlorohydrin-formaldehyde-phenol copolymer	9003-36-5	2.49 E-05	3.11	31100	0.07	741
Other organic materials	Epoxy resin, epichlorohydrin-dimer fatty acid	68475-94-5	2.49 E-05	3.11	31100	0.07	741
Other organic materials	Butyrolactone, gamma-	96-48-0	2.49 E-05	3.11	31100	0.07	741
Other organic materials	Poly(oxypropylene)diamine	9046-10-0	2.49 E-05	3.11	31100	0.07	741
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	2.49 E-05	3.11	31100	0.07	741
Other organic materials	Organosilane	TS ref# 10001	2.49 E-05	3.11	31100	0.07	741
Other inorganic materials	Copper(II) oxide	1317-38-0	2.49 E-05	3.11	31100	0.07	741
Other organic materials	Epoxy resin modifier	TS ref# 10038	4.16 E-06	0.52	5200	0.01	124
Subtotal			8.00 E-04	100.00	1000000	2.38	23831

Die Coat

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other organic materials	Polydimethylsiloxane	Proprietary	2.26 E-04	100.00	1000000	0.672	6717

Lid/ Shield Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.69 E-04	75.0	744493	0.50	5034
Other organic materials	Bisphenof F type epoxy resin	9003-36-5	2.30 E-05	10.0	101322	0.07	685
Other organic materials	Bisphenof A type epoxy resin	25068-38-6	2.30 E-05	10.0	101322	0.07	685
Others	Additives	Proprietary	7.00 E-06	3.0	30837	0.02	209
Others	Curing Agent	Proprietary	5.00 E-06	2.0	22026	0.01	149
Subtotal			2.27 E-04	100.00	1000000	0.68	6762

	Weight (g)	Percentage (%)	PPM
Package Totals	**3.36 E-02**	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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